



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|--------------|-------------------------------|---|-------------|-----------------|
| Applicant: | Jing Cheng Lin, et al. | § | Docket No.: | 24061.485 |
| | | § | | (TSMC2002-0360) |
| Serial No.: | 10/618,536 | § | | |
| | | § | Examiner: | Thien F. Tran |
| Filing Date: | June 11, 2003 | § | | |
| | | § | Art Unit: | 2811 |
| For: | Adhesion Copper and Etch Stop | § | | |
| | Layer for Copper Alloy | § | Conf. No.: | 5026 |
| | | § | | |

TRANSMITTAL

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Response to Restriction Requirement;
2. Petition for Extension of Time (1-month);
3. Check in the amount of \$110.00; and
4. Return Receipt Postcard

The Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell
Reg. No. 42,044

Date: 10-20-04

HAYNES AND BOONE, LLP
901 Main Street, Suite 3100
Dallas, Texas 75202-3789
Telephone: 972-739-8635
Facsimile: 214-200-0853

Customer Number: 42717

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box: Amendments, Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

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